



**ALPHA & OMEGA**  
SEMICONDUCTOR, INC.

Sep 2002

**AO7400**

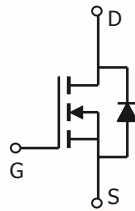
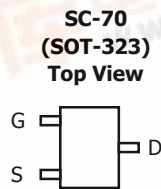
**N-Channel Enhancement Mode Field Effect Transistor**

**General Description**

The AO7400 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V, in the small SOT323 footprint. It can be used for a wide variety of applications, including load switching, low current inverters and low current DC-DC converters.

**Features**

- $V_{DS}$  (V) = 30V
- $I_D$  = 1.7 A
- $R_{DS(ON)} < 85m\Omega$  ( $V_{GS} = 10V$ )
- $R_{DS(ON)} < 100m\Omega$  ( $V_{GS} = 4.5V$ )
- $R_{DS(ON)} < 140m\Omega$  ( $V_{GS} = 2.5V$ )



**Absolute Maximum Ratings  $T_A=25^\circ C$  unless otherwise noted**

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>A</sup>	$I_D$	$T_A=25^\circ C$	1.7
		$T_A=70^\circ C$	1.3
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	10	A
Power Dissipation <sup>A</sup>	$P_D$	$T_A=25^\circ C$	0.35
		$T_A=70^\circ C$	0.22
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	300	360	$^\circ C/W$
Maximum Junction-to-Ambient <sup>A</sup>		Steady-State	340	425
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	280	320	$^\circ C/W$



Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			1 5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.6	1	1.4	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =5V	10			A
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =1.5A T <sub>J</sub> =125°C		70 100	85 125	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =1.5A		81	100	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =1A		114	140	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =1.5A		4		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1A, V <sub>GS</sub> =0V		0.81	1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				0.5	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		390		pF
C <sub>oss</sub>	Output Capacitance			54.5		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			41		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		3		Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =15V, I <sub>D</sub> =1.7A		4.82		nC
Q <sub>gs</sub>	Gate Source Charge			0.62		nC
Q <sub>gd</sub>	Gate Drain Charge			1.58		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =10.0Ω, R <sub>GEN</sub> =3Ω		2.5		ns
t <sub>r</sub>	Turn-On Rise Time			2.3		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			22		ns
t <sub>f</sub>	Turn-Off Fall Time			3		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =1.7A, dI/dt=100A/μs		10		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =1.7A, dI/dt=100A/μs		3.6		nC

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any a given application depends on the user's specific board design. The current rating is based on the t<sub>s</sub> ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

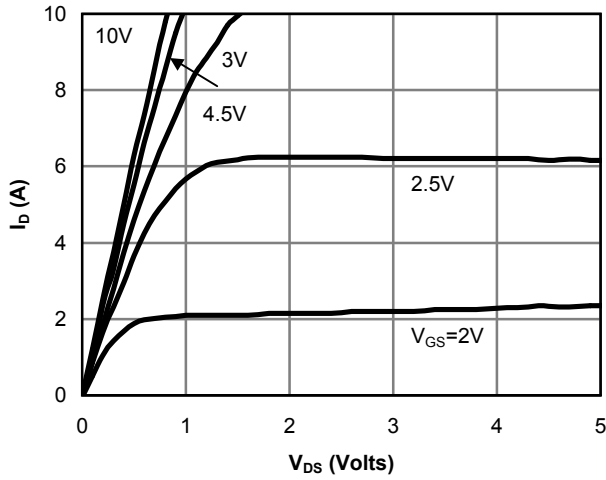


Fig 1: On-Region Characteristics

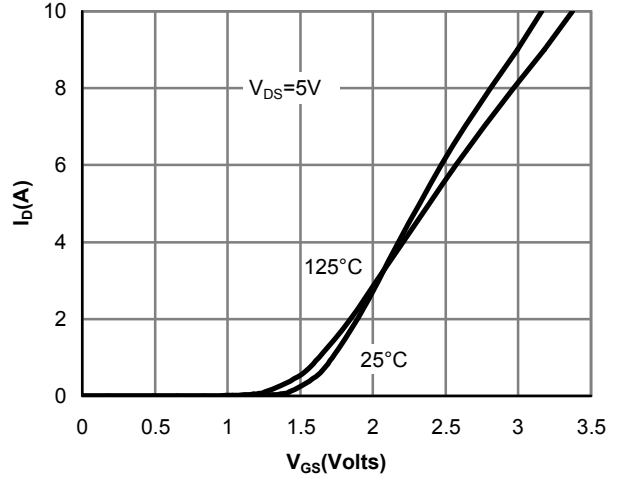


Figure 2: Transfer Characteristics

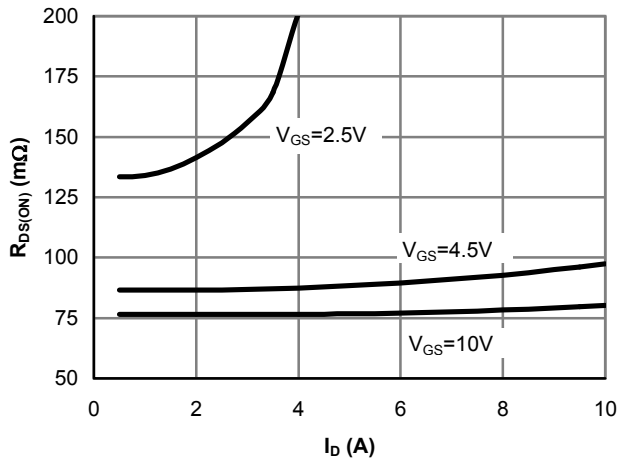


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

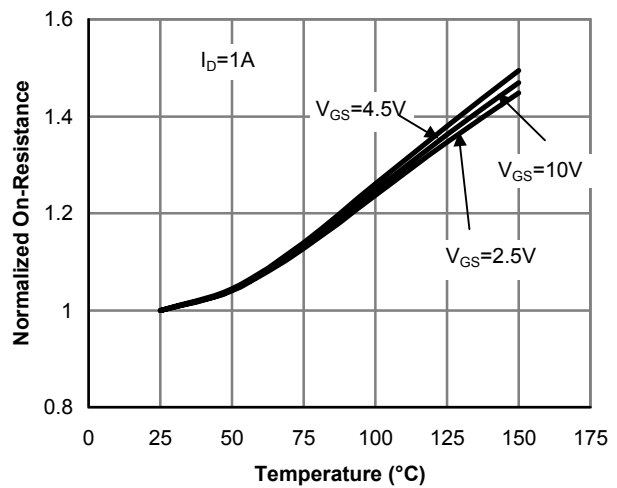


Figure 4: On-Resistance vs. Junction Temperature

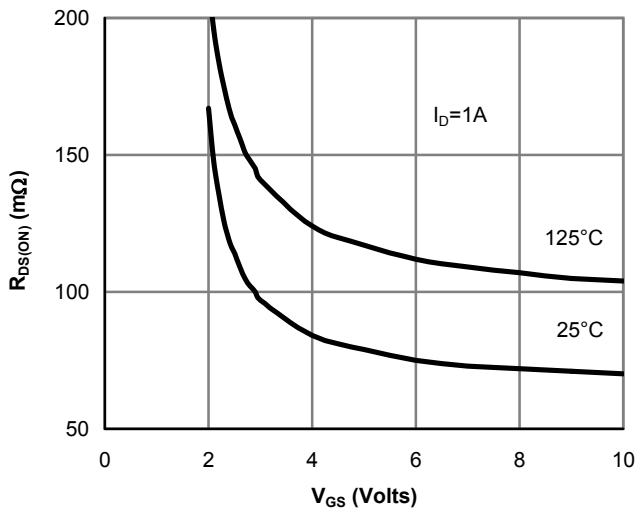


Figure 5: On-Resistance vs. Gate-Source Voltage

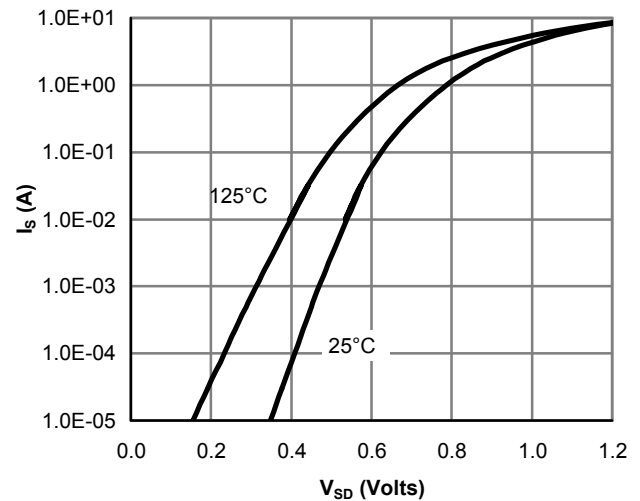


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

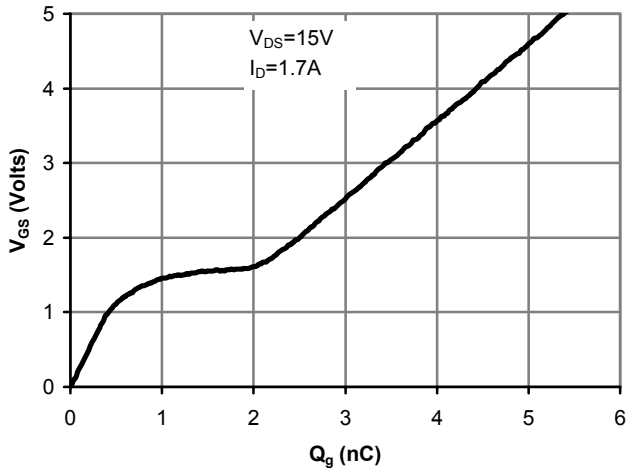


Figure 7: Gate-Charge Characteristics

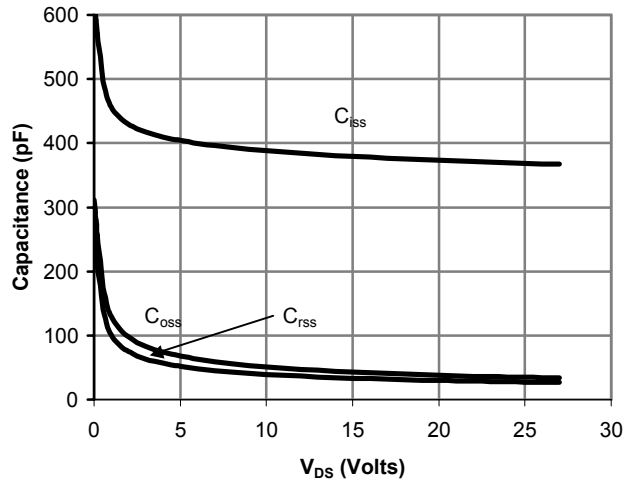


Figure 8: Capacitance Characteristics

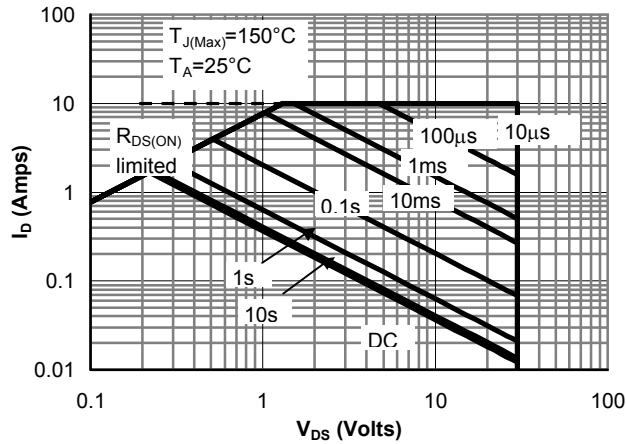


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

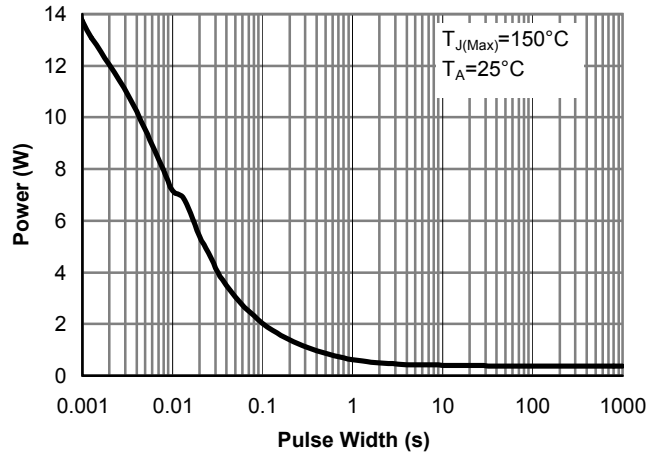


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

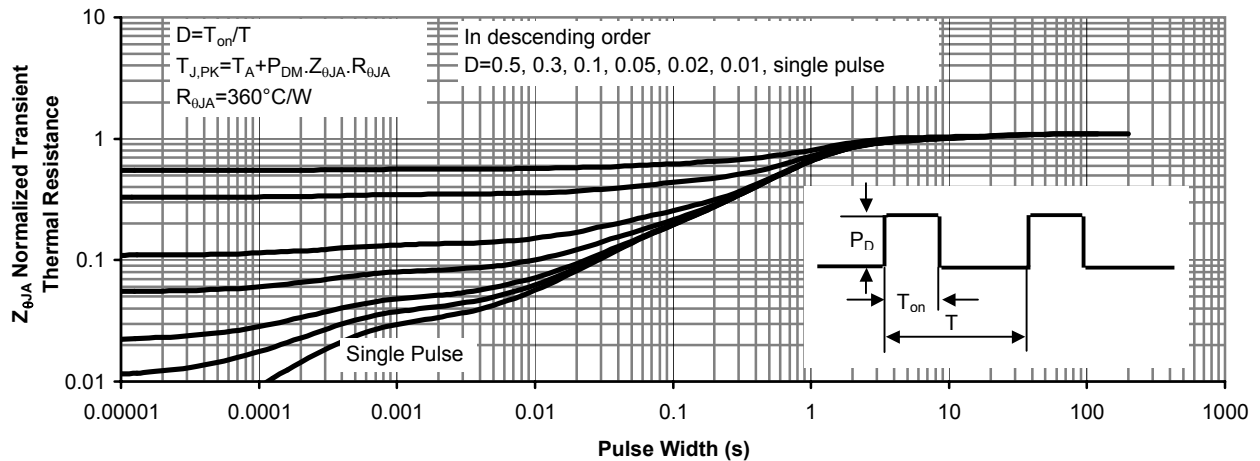
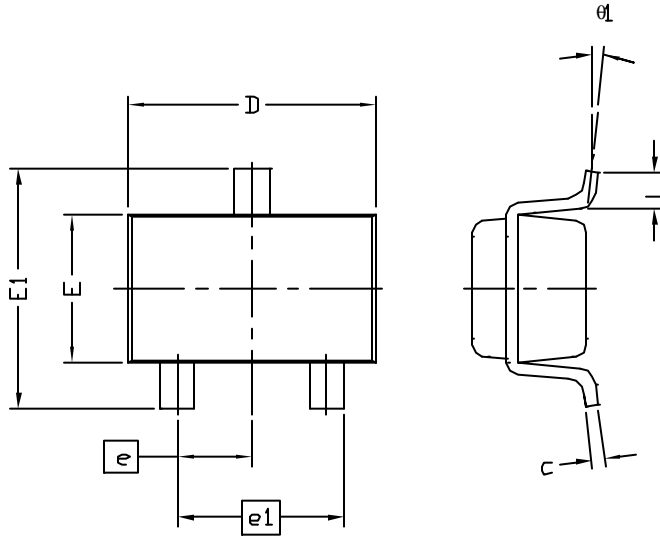


Figure 11: Normalized Maximum Transient Thermal Impedance



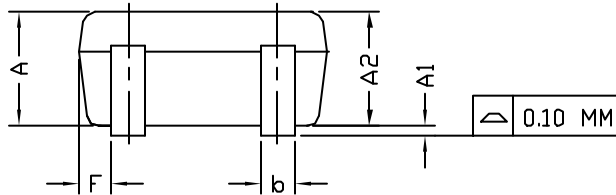
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### SC-70 3L Package Data



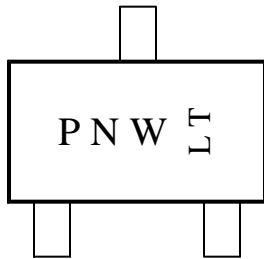
SYMBOLS	DIMENSIONS IN MILLIMETERS	
	MIN	MAX
A	0.90	1.10
A1	0.00	0.10
A2	0.90	1.00
b	0.25	0.40
C	0.10	0.20
D	1.80	2.20
E	1.15	1.35
E1	2.00	2.20
F	0.30	0.40
e	0.65 BSC	
e1	1.30 BSC	
L	0.10	0.30
θ1	1°	8°

- NOTE:  
 1. LEAD FINISH: 150 MICRONS (3.8 um) MIN.  
 THICKNESS OF Tin/Lead (SOLDER) PLATED ON LEAD  
 2. TOLERANCE ±0.10 mm (4 mil) UNLESS OTHERWISE SPECIFIED  
 3. COPLANARITY : 0.10 mm  
 4. OTHER NAME OF THIS PACKAGE IS CALLED SOT-323



PACKAGE MARKING DESCRIPTION

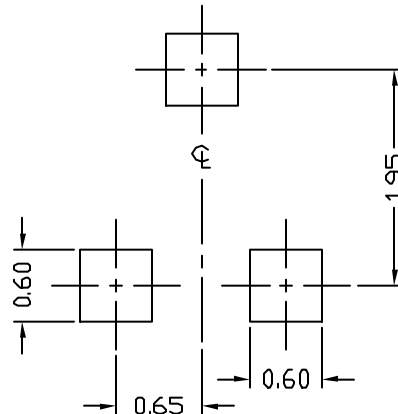
RECOMMENDATION OF LAND PATTERN



SC-70 3L PART NO. CODE

PART NO.	CODE
AO7400	0

- NOTE:  
 P - PART NUMBER CODE.  
 N - FOUNDRY AND ASSEMBLY LOCATION CODE  
 W - YAER AND WEEK CODE.  
 L T - ASSEMBLY LOT CODE.

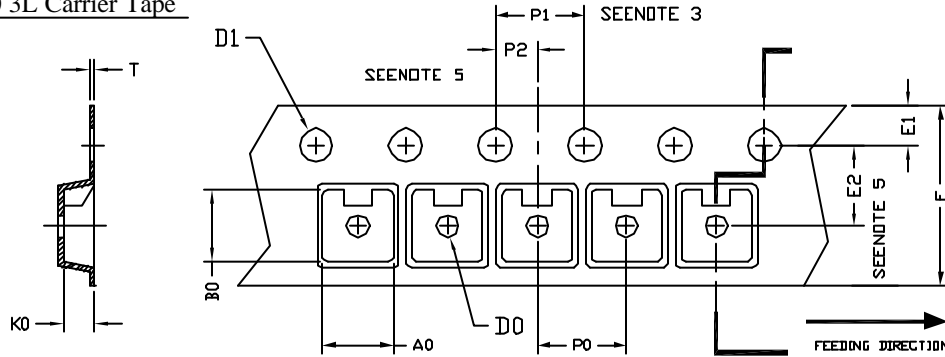




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## SC-70 3L Tape and Reel Data

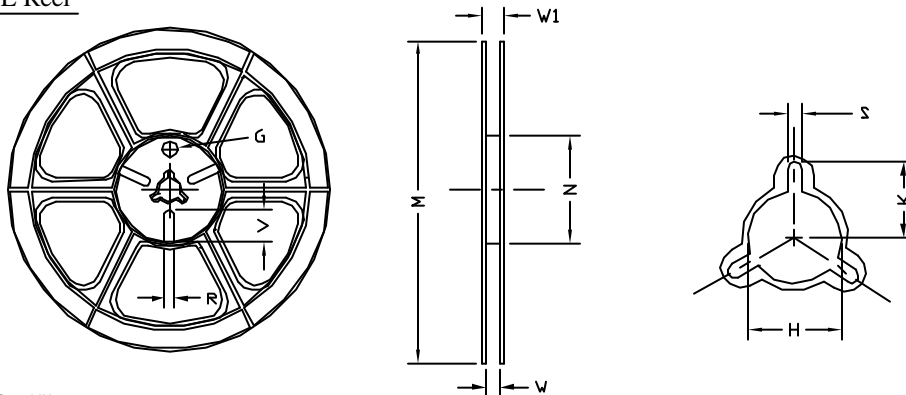
### SC-70 3L Carrier Tape



UNIT: MM

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SC-70, 3L (B mm)	2.40 ±0.10	2.40 ±0.10	1.19 ±0.10	1.00 MIN	1.55 ±0.05	8.00 ±0.30	1.75 ±0.10	3.50 ±0.05	4.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.25 ±0.05

### SC-70 3L Reel



UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
8 mm	ø180	ø180.00 ±0.50	ø60.50	9.00 ±0.30	11.40 ±1.00	ø13.00 +0.50 -0.20	10.60	2.00 ±0.50	ø9.00	5.00	18.00

### SC-70 3L Tape

Leader / Trailer  
& Orientation

